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- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable

description/ordering information

The 'AC163 devices are 4-bit binary counters. These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs

CD54AC163...F PACKAGE CD74AC163...E OR M PACKAGE (TOP VIEW) CLR 16 V_{CC} CLK 2 15 RCO А∐з 14 Q_A B 🛮 4 13 Q_B C 🛮 5 12 Q_C D 🛮 6 11 Q_D 10 ENT ENP [] 7 9 LOAD GND II

change, coincident with each other, when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

The counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. Presetting is synchronous; therefore, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function is synchronous. A low level at the clear ($\overline{\text{CLR}}$) input sets all four of the flip-flop outputs low after the next low-to-high transition of CLK, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to $\overline{\text{CLR}}$ to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP, ENT, and a ripple-carry output (RCO) are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15, with Q_A high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These devices feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or $\overline{\text{LOAD}}$) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

ORDERING INFORMATION

TA	PAC	KAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74AC163E	CD74AC163E
–55°C to 125°C	SOIC - M	Tube	CD74AC163M	AC163M
-55 C to 125 C	SOIC - W	Tape and reel	CD74AC163M96	AC 103W
	CDIP – F	Tube	CD54AC163F3A	CD54AC163F3A

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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FUNCTION TABLE

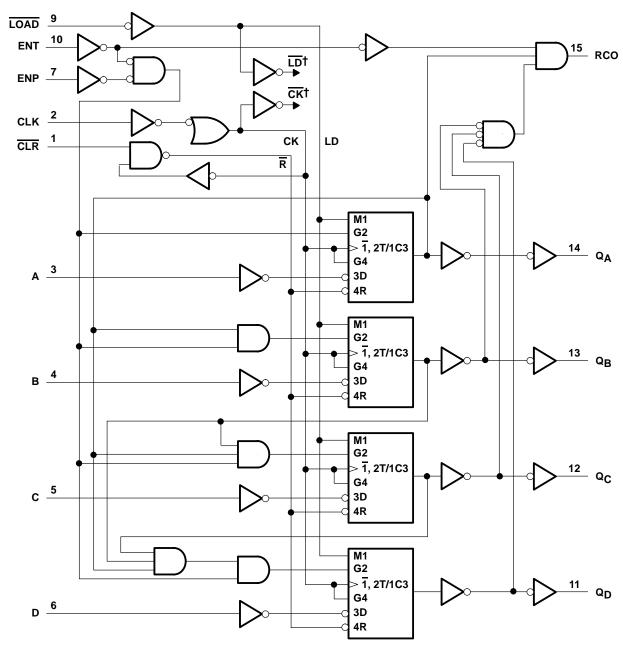
		IN	IPUTS			OUTPUTS		FUNCTION
CLR	CLK	ENP	ENT	LOAD	A,B,C,D	Qn	RCO	FUNCTION
L	↑	Χ	Χ	Χ	Χ	L	L	Reset (clear)
h	↑	Х	Х	I	I	L	L	Parallel load
h	\uparrow	Χ	Χ	I	h	Н	Note 1	Parallel load
h	↑	h	h	h	Χ	Count	Note 1	Count
h	Χ	!	Χ	h	Х	q _n	Note 1	Inhibit
h	Χ	Χ	I	h	Χ	q _n	L	HIHIDIC

H = high level, L = low level, X = don't care, h = high level one setup time prior to the CLK low-to-high transition, I = low level one setup time prior to the CLK low-to-high transition, q = the state of the referenced output prior to the CLK low-to-high transition, and \uparrow = CLK low-to-high transition.

NOTE 1: The RCO output is high when ENT is high and the counter is at terminal count (HHHH).



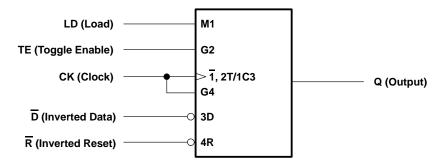
logic diagram (positive logic)



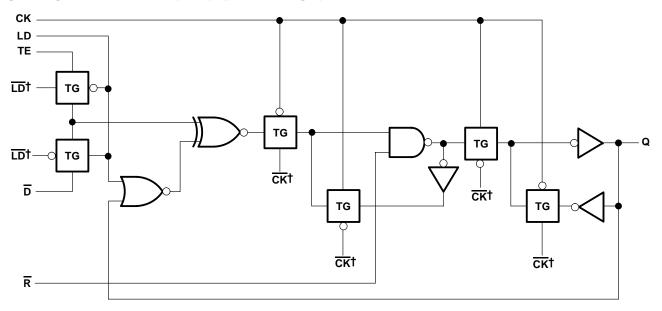
[†] For simplicity, routing of complementary signals $\overline{\mathsf{LD}}$ and $\overline{\mathsf{CK}}$ is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

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logic symbol, each D/T flip-flop



logic diagram, each D/T flip-flop (positive logic)

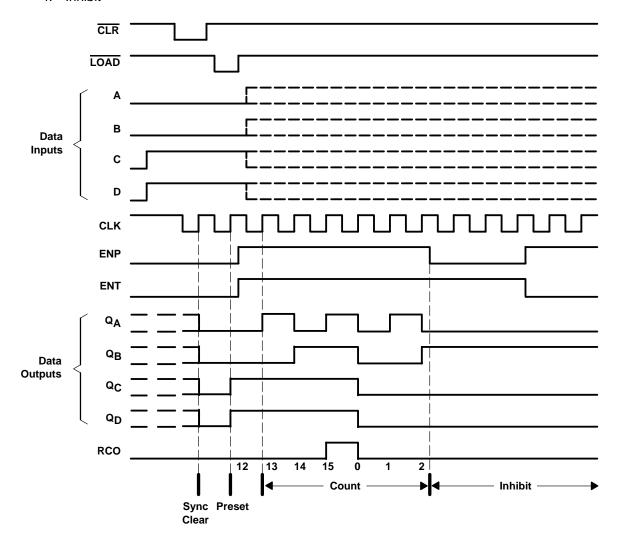


 $^{^{\}dagger}$ The origins of \overline{LD} and \overline{CK} are shown in the logic diagram of the overall device.

typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (synchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 2)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 2)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): E package	67°C/W
M package	
Storage temperature range, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 4)

			T _A = 2	25°C	–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V _{CC} = 1.5 V	1.2		1.2		1.2		
VIH	High-level input voltage	VCC = 3 V	2.1		2.1		2.1		V
		V _{CC} = 5.5 V	3.85		3.85		3.85		
		V _{CC} = 1.5 V		0.3		0.3		0.3	
VIL	Low-level input voltage	VCC = 3 V		0.9		0.9		0.9	V
		V _{CC} = 5.5 V		1.65		1.65		1.65	
VI	Input voltage		0	VCC	0	VCC	0	VCC	V
Vo	Output voltage		0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current			-24		-24		-24	mA
loL	Low-level output current			24		24		24	mA
A+/A>/	Input transition rise or fall rate	V _{CC} = 1.5 V to 3 V		50		50		50	20
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$		20		20		20	ns

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{3.} The package thermal impedance is calculated in accordance with JESD 51-7.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX		
			1.5 V	1.4		1.4		1.4			
		I _{OH} = -50 μA	3 V	2.9		2.9		2.9			
			4.5 V	4.4		4.4		4.4			
Voн	$V_I = V_{IH}$ or V_{IL}	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V	
		$I_{OH} = -24 \text{ mA}$	4.5 V	3.94		3.7		3.8			
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V	-		3.85		_			
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V	_		_		3.85			
		I _{OL} = 50 μA	1.5 V		0.1		0.1		0.1		
			I _{OL} = 50 μA	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1		
VOL	VI = VIH or VIL	I _{OL} = 12 mA	3 V		0.36		0.5		0.44	V	
		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44		
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V		-		1.65		-		
	I _{OL}	I _{OL} = 75 mA [†]	5.5 V		-		_		1.65		
lį	V _I = V _{CC} or GND		5.5 V		±0.1		±1		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μΑ	
C _i		·			10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			VCC	–55° 125		–40°(85°		UNIT
1				MIN	MAX	MIN	MAX	
			1.5 V		7		8	
f _{clock}	Clock frequency		$3.3 \text{ V} \pm 0.3 \text{ V}$		64		73	MHz
			5 V ± 0.5 V		90		103	
			1.5 V	69		61		
t _W	Pulse duration	CLK high or low	$3.3~V \pm 0.3~V$	7.7		6.8		ns
			5 V ± 0.5 V	5.5		4.8		
			1.5 V	63		55		
		A, B, C, or D	$3.3 \text{ V} \pm 0.3 \text{ V}$	7		6.1		
			5 V ± 0.5 V	5		4.4		
			1.5 V	63		55		ns
		ENP or ENT	$3.3~V \pm 0.3~V$	9.6		8.2		
١.	Catum times hatana CLIVA		5 V ± 0.5 V	5		4.4		
t _{su}	Setup time, before CLK↑		1.5 V	75		66		
		LOAD low	$3.3 \text{ V} \pm 0.3 \text{ V}$	8.4		7.4		
			5 V ± 0.5 V	6		5.3		
			1.5 V	75		66		
		CLR inactive	$3.3~V \pm 0.3~V$	8.4		7.4		
			5 V ± 0.5 V	6		5.3		
			1.5 V	0		0		
		A, B, C, or D	$3.3 \text{ V} \pm 0.3 \text{ V}$	0		0		
			5 V ± 0.5 V	0		0		1
			1.5 V	0		0		
		ENP or ENT	3.3 V ± 0.3 V	0		0		
١.	Haldfara after OUA		5 V ± 0.5 V	0		0		_
th	Hold time, after CLK↑		1.5 V	0		0		ns
		LOAD low	3.3 V ± 0.3 V	0		0		
			5 V ± 0.5 V	0		0		
			1.5 V	0		0		
		CLR inactive	3.3 V ± 0.3 V	0		0		
			5 V ± 0.5 V	0		0		

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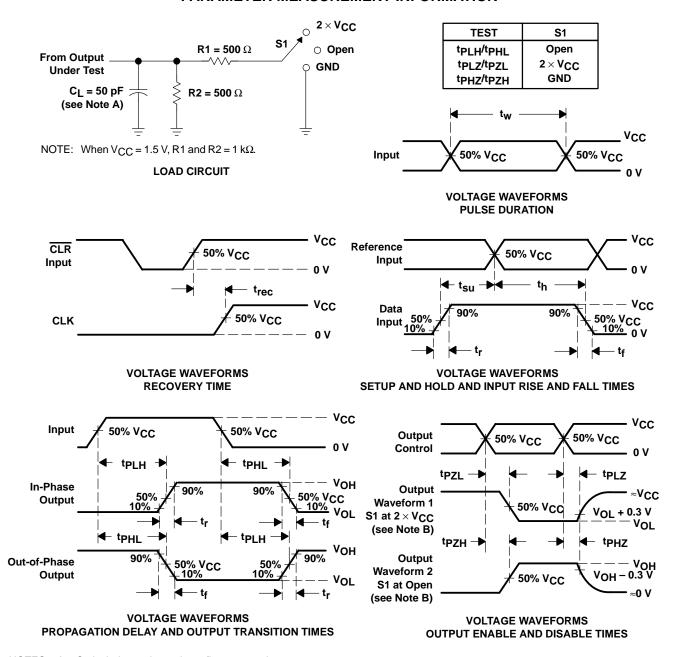
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	Vcc	–55°(125		–40°(85°		UNIT
	(INFOT)	(0011-01)		MIN	MAX	MIN	MAX	
			1.5 V	7		8		
f _{max}			$3.3~\text{V}\pm0.3~\text{V}$	64		73		MHz
			5 V ± 0.5 V	90		103		
	CLK	RCO	1.5 V	-	209	_	190	
			$3.3~\text{V}\pm0.3~\text{V}$	6	23.4	6	21	
			5 V ± 0.5 V	4.3	16.7	4.3	15.2	
		Any Q	1.5 V	-	207	-	188	ns
^t pd			$3.3~\text{V}\pm0.3~\text{V}$	5.9	23.1	5.9	21	
			5 V ± 0.5 V	4.2	16.5	4.2	15	
		RCO	1.5 V	_	129	-	117	
	ENT		$3.3~\text{V}\pm0.3~\text{V}$	3.6	14.4	3.7	13.1	
			5 V ± 0.5 V	2.6	10.3	2.7	9.4	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	66	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$. Phase relationships between waveforms are arbitrary.
- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. t_{PLH} and t_{PHL} are the same as t_{pd} .
- G. tpzL and tpzH are the same as ten.
- H. tpLz and tpHz are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



14 LEADS SHOWN



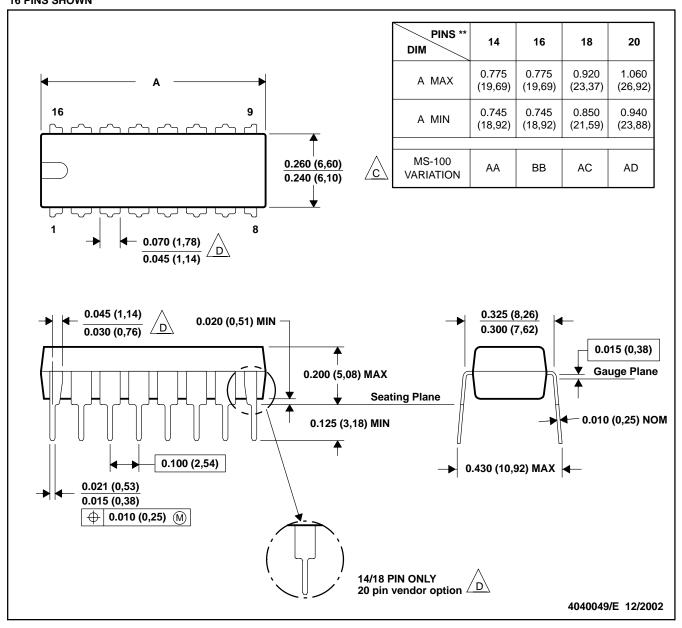
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

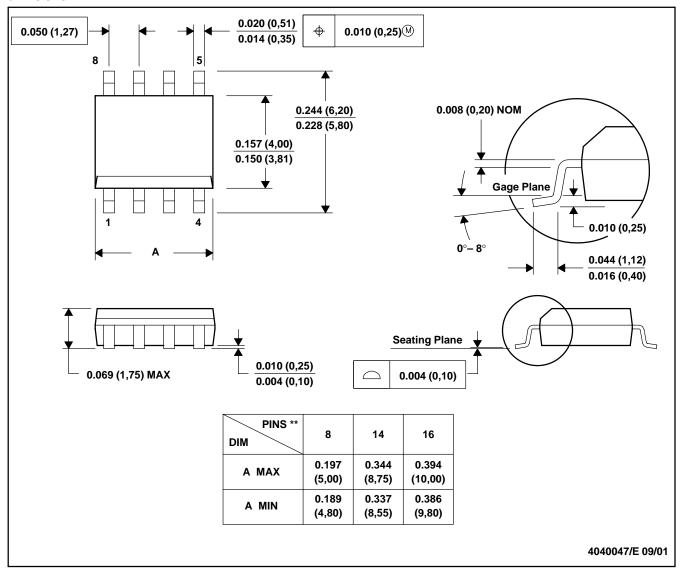
The 20 pin end lead shoulder width is a vendor option, either half or full width.

1

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

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